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Title of Invention: SEMICONDUCTOR PACKAGE AND
METHOD OF MAKING
LEADFRAME HAVING LEAD
LOCKS TO SECURE LEADS TO
ENCAPSULANT

First Named Inventor: Jae Yee

Domestic/Foreign Application: Domestic Application

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Electronic Version v1.1
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Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT	
Application Number:	10/667227	
Date:	2003-09-18	
First Named Applicant:	Jae Hak Yee	
Confirmation Number:	7012	
Attorney Docket Number:	AMKOR012G1	
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Submitted by:	Elec. Sign.	Sign. Capacity
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney
Documents being submitted us-ids	Files ids3-usidst.xml us-ids.dtd us-ids.xsl	
Comments		



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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Application Number: 10/667227



Confirmation Number: 7012

First Named Applicant: Jae Yee

Attorney Docket Number: AMKOR012G1

Art Unit: 2812

Search string: (5640047 or 5639990 or 5641997 or 5644169
or 5643433 or 5646831 or 5650663 or 5661088
or 5665996 or 5673479 or 5683806 or 5689135
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or 5724233 or 5723899 or 5736432 or 5745984
or 5753977 or 5753532 or 5766972 or 5770888
or 5776798 or 5783861 or 5801440 or 5814884
or 5814883 or 5814881 or 5814877 or 5818105
or 5817540 or 5821615 or 5821457 or 5835988
or 5834830 or 5844306 or 5856911 or 5859471
or 5866939 or 5871782 or 5874784 or 5877043
or 5886398 or 5886397 or 5894108 or 5897339
or 5900676 or 5903050).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Signature

Examiner Name	Date